



US 20220386466A1

(19) **United States**(12) **Patent Application Publication**
YOKOMIZO et al.(10) **Pub. No.: US 2022/0386466 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **ELECTRONIC COMPONENT****H01G 4/12** (2006.01)**H01G 4/30** (2006.01)(71) Applicant: **Murata Manufacturing Co., Ltd.**,
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(2013.01); **H01G 4/012** (2013.01); **H01G**
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ABSTRACT

An electronic component includes an electronic element and an interposer board. The electronic element includes a multilayer body and external electrodes at multilayer body end surfaces and connected to internal electrode layers. The interposer board includes board end surfaces, board side surfaces orthogonal to the board end surfaces, and board main surfaces orthogonal to the board end surfaces and the board side surfaces. One of the board main surfaces is in a vicinity of the electronic element and is joined with one of the multilayer body main surfaces in a vicinity of the interposer board. The interposer board is an alumina board. A maximum length of the interposer board is smaller than a length of the electronic element. A width of the interposer board is smaller than a width of the electronic element.

(21) Appl. No.: **17/752,896**(22) Filed: **May 25, 2022**(30) **Foreign Application Priority Data**

May 31, 2021 (JP) 2021-091538

Publication Classification(51) **Int. Cl.****H05K 1/18** (2006.01)**H01G 4/008** (2006.01)**H01G 4/012** (2006.01)